



VIKING INTERWORKS DIVISION OF SANMINA-SCI LAUNCHES RDRAM NEXMOD PRODUCT: "DROP-IN" RAMBUS CHANNEL SUBSYSTEM IDEAL FOR NETWORK PROCESSORS

License Agreement Provides Comprehensive Channel Expansion for HCD's Innovative Memory Solutions

SAN JOSE, Calif., (August 20, 2002) — Viking Interworks, a Sanmina-SCI Company (Nasdaq NM: SANM), announced today that it has licensed the RDRAM NexMod technology from High Connection Density, Inc. (HCD). The RDRAM NexMod is a "drop-in" memory solution that delivers a complete Rambus channel in one subsystem – simplifying customer board design and reducing mainboard costs. Ideal for network processors that require RDRAM for packet buffer memory, the RDRAM NexMod is also very small in form factor, saving up to 60% of the mainboard real estate versus competing solutions. The RDRAM NexMod is available in both commercial and industrial temperature ranges, with or without ECC, in densities ranging from 64MB to 288MB using 256/288Mb RDRAM components or up to 576MB with 576Mb components.

"The networking and communications market represent a significant growth area for DRAM and memory usage," said Ralph Kaplan, Executive Vice President and General Manager of the Viking Interworks Modular Solutions Division of Sanmina-SCI. "This is especially true for applications using network processors where packet buffer memory densities are increasing significantly to support data transmission rates of 10Gbps and beyond. HCD has pioneered an innovative solution that will enable the world's leading systems design teams to get to market faster with a high performance memory solution."

The NexMod technology, as well as the RDRAM NexMod product, were initially pioneered by HCD to solve the memory needs of networking applications. "HCD is extremely excited to be working together with Sanmina-SCI in order to meet industry requirements for multiple sources of the RDRAM NexMod," said Dirk Brown, Executive Vice President of Business Development at HCD.

The RDRAM NexMod offers a complete Rambus channel in one subsystem which means it includes termination resistors, the Direct Rambus Clock Generator (DRCG), and the Voltage Regulator Module (VRM) on the same modular subsystem as the memory chips. The RDRAM NexMod is less than 0.5 inches in height and measures 1.1 inches x 2.0 inches in size. Flexibility is enhanced by allowing attachment to the mainboard in two ways: with pin grid array (PGA) connectors for a field upgradeable solution or soldered directly to the mainboard using ball grid array (BGA) technology. In order to meet the strict requirements of telecommunications equipment, the RDRAM NexMod comes in both commercial and industrial temperature ranges. RDRAM NexMod is currently available at speed grades of 800MHz and 1066MHz in both PGA and BGA connections. Current density configurations are 64/72MB, 128/144MB, and 256/288MB. For product data sheets or more information on the RDRAM NexMod, please contact the Viking Interworks Modular Solutions Division of Sanmina-SCI at oemsales@vikingcomponents.com.



HIGH CONNECTION DENSITY, INC.
www.hcdcorp.com

About Sanmina-SCI

Sanmina-SCI Corporation is a leading electronics contract manufacturer serving the fastest-growing segments of the \$130 billion global electronics manufacturing services (EMS) market. Recognized as a technology leader, Sanmina-SCI provides end-to-end manufacturing solutions, delivering unsurpassed quality and support to large OEMs primarily in the communications, defense and aerospace, industrial and medical instrumentation, computer technology and multimedia sectors of the market. Sanmina-SCI has over 100 facilities strategically located in key regions throughout the world. For further information on the company, visit the website at www.sanmina-sci.com.

About High Connection Density, Inc.

High Connection Density, Inc. (HCD) views its business as enabling customers to utilize the latest advancements in technology. By providing engineered solutions for its customers, HCD leads the electronics industry as the premier source of innovative high frequency and high current, form factor optimized solutions through advanced electronics packaging and connection technologies. To learn more about HCD products and services, visit the website at www.hcdcorp.com.

Safe Harbor Statement

The foregoing, including the discussion regarding the company's future prospects, contains certain forward-looking statements that involve risks and uncertainties, including uncertainties associated with economic conditions in the electronics industry, particularly in the principal industry sectors served by the company, changes in customer requirements and in the volume of sales to principal customers, the ability of Sanmina-SCI to effectively integrate its operations following the merger of Sanmina Corporation and SCI Systems, Inc. and to assimilate other acquired businesses and achieve the anticipated benefits of the merger and other such acquisitions, and competition and technological change. The company's actual results of operations may differ significantly from those contemplated by such forward-looking statements as a result of these and other factors, including factors set forth in the company's 2001 Annual Report on Form 10-K and 10K/A filed with the Securities Exchange Commission on December 21, 2001 and March 26, 2002 and the company's 10-Q filed with the Securities Exchange Commission on August 12, 2002.